



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Features

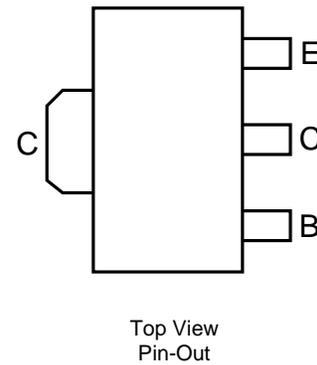
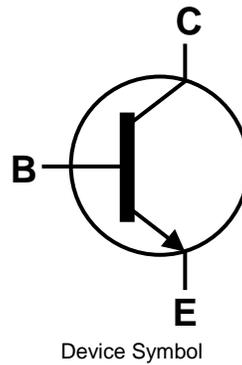
- $BV_{CEO} > 50V$
- $I_C = 3.0A$ Continuous Current
- Complementary PNP Type Available (DPLS350Y)
- Ideally Suited for Automated Assembly Processes

Mechanical Data

- Package: SOT89
- Package Material: Molded Plastic, "Green" Molding Compound
UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 
- Weight: 0.052 grams (Approximate)

Applications

- Medium power switching or amplification



Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|------------------------------|-----------|-------|------|
| Collector-Base Voltage | V_{CBO} | 50 | V |
| Collector-Emitter Voltage | V_{CEO} | 50 | V |
| Emitter-Base Voltage | V_{EBO} | 5 | V |
| Peak Pulse Collector Current | I_{CM} | 5 | A |
| Continuous Collector Current | I_C | 3 | A |
| Base Current | I_B | 0.5 | A |

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|---|-----------------|-------------|--------------------|
| Power Dissipation | P_D | (Note 5) | 1 |
| | | (Note 6) | 1.6 |
| | | (Note 7) | 2.0 |
| Thermal Resistance, Junction to Ambient Air | $R_{\theta JA}$ | (Note 5) | 125 |
| | | (Note 6) | 78 |
| | | (Note 7) | 62.5 |
| Thermal Resistance, Junction to Lead | $R_{\theta JL}$ | 5.7 | $^\circ\text{C/W}$ |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ\text{C}$ |

ESD Ratings (Note 9)

| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | C |

- Notes:
5. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 6. Same as note (5), except the device is mounted on 25mm x 25mm 1oz copper.
 7. Same as note (5), except the device is mounted on 50mm x 50mm 1oz copper.
 8. Thermal resistance from junction to solder-point (on the exposed collector pad).
 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

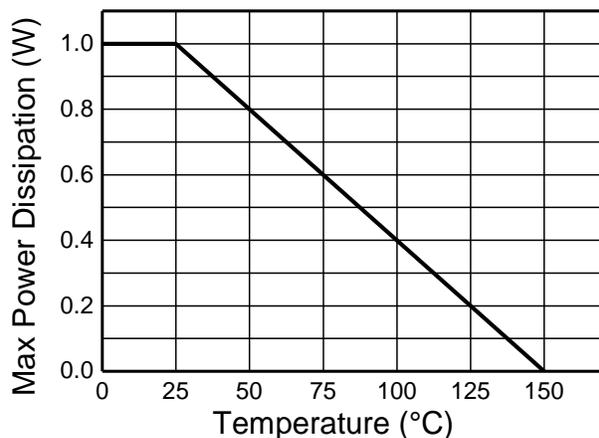


Figure 1. Derating Curve

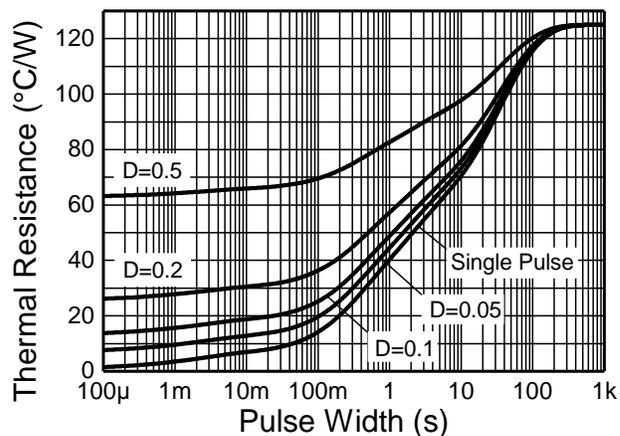


Figure 2. Transient Thermal Resistance

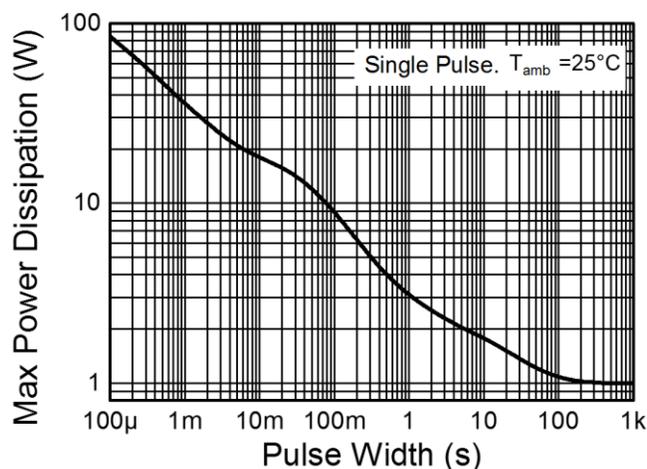


Figure 3. Pulse Power Dissipation

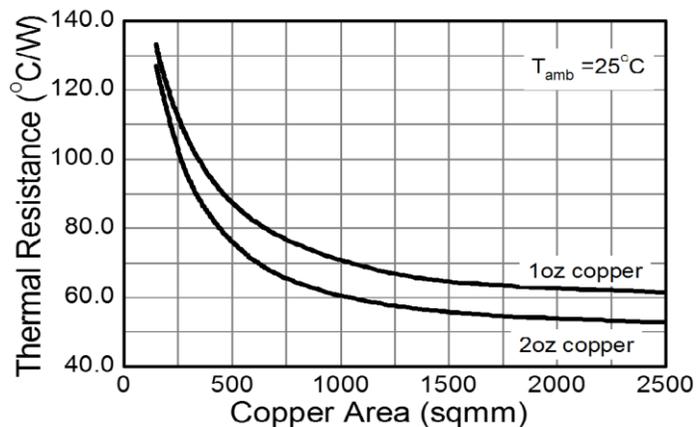


Figure 4. Rthja vs Area

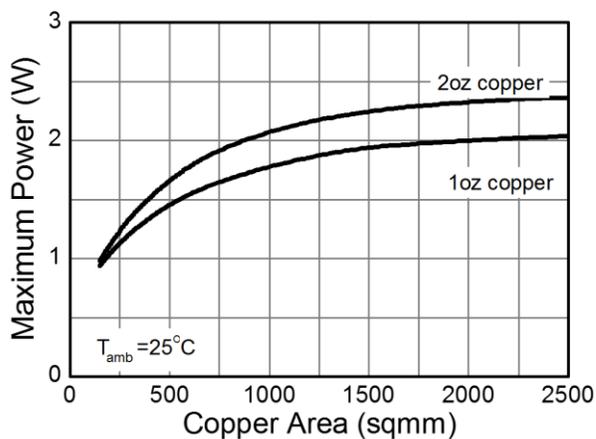


Figure 5. Max Power vs Area

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Typ | Max | Unit | Test Condition |
|--------------------------------------|----------------------|-----|-----|-----|------|---|
| OFF CHARACTERISTICS (Note 10) | | | | | | |
| Collector-Base Cutoff Current | I _{CB0} | — | — | 100 | nA | V _{CB} = 50V |
| | | — | — | 50 | μA | V _{CB} = 50V, T _A = +150°C |
| Emitter-Base Cutoff Current | I _{EBO} | — | — | 100 | nA | V _{EB} = 5V |
| Collector-Emitter Cutoff Current | I _{CES} | — | — | 100 | nA | V _{CE} = 50V, V _{BE} = 0 |
| Collector-Base Breakdown Voltage | BV _{CB0} | 50 | — | — | V | I _C = 100μA |
| Collector-Emitter Breakdown Voltage | BV _{CEO} | 50 | — | — | V | I _C = 10mA |
| Emitter-Base Breakdown Voltage | BV _{EBO} | 5 | — | — | V | I _E = 100μA |
| ON CHARACTERISTICS (Note 10) | | | | | | |
| DC Current Gain | h _{FE} | 300 | — | — | — | V _{CE} = 2V, I _C = 0.1A |
| | | 300 | — | — | | V _{CE} = 2V, I _C = 0.5A |
| | | 300 | — | 700 | | V _{CE} = 2V, I _C = 1A |
| | | 200 | — | — | | V _{CE} = 2V, I _C = 2A |
| | | 100 | — | — | | V _{CE} = 2V, I _C = 3A |
| Collector-Emitter Saturation Voltage | V _{CE(sat)} | — | 38 | 80 | mV | I _C = 0.5A, I _B = 50mA |
| | | — | 70 | 160 | | I _C = 1A, I _B = 50mA |
| | | — | 130 | 280 | | I _C = 2A, I _B = 100mA |
| | | — | 124 | 260 | | I _C = 2A, I _B = 200mA |
| | | — | 180 | 370 | | I _C = 3A, I _B = 300mA |
| Equivalent On-Resistance | R _{CE(sat)} | — | 62 | 130 | mΩ | I _E = 2A, I _B = 200mA |
| Base-Emitter Saturation Voltage | V _{BE(sat)} | — | — | 1.1 | V | I _C = 2A, I _B = 100mA |
| | | — | — | 1.2 | V | I _C = 3A, I _B = 300mA |
| Base-Emitter Turn-on Voltage | V _{BE(on)} | — | — | 1.1 | V | V _{CE} = 2V, I _C = 1A |
| SMALL SIGNAL CHARACTERISTICS | | | | | | |
| Transition Frequency | f _T | 100 | — | — | MHz | V _{CE} = 5V, I _C = 100mA, f = 100MHz |
| Output Capacitance | C _{obo} | — | — | 25 | pF | V _{CB} = 10V, f = 1MHz |

Note: 10. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

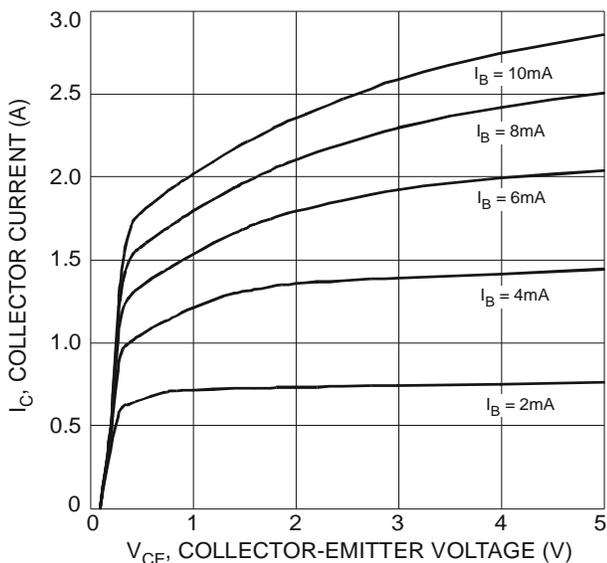


Figure 6. Typical Collector Current vs Collector-Emitter Voltage

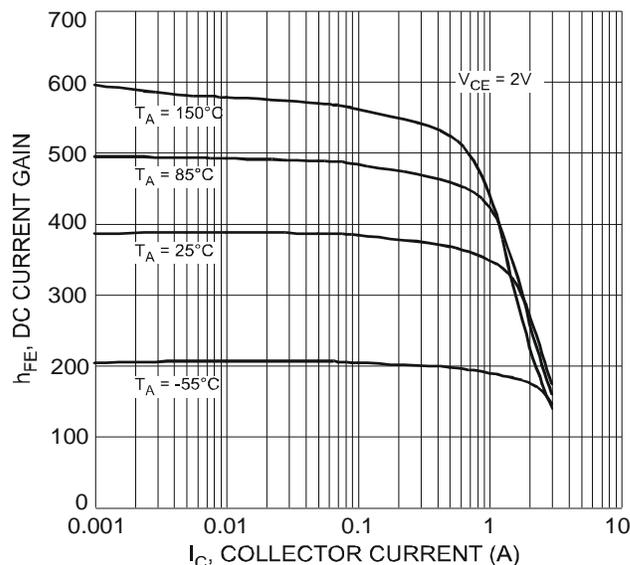


Figure 7. Typical DC Current Gain vs Collector Current

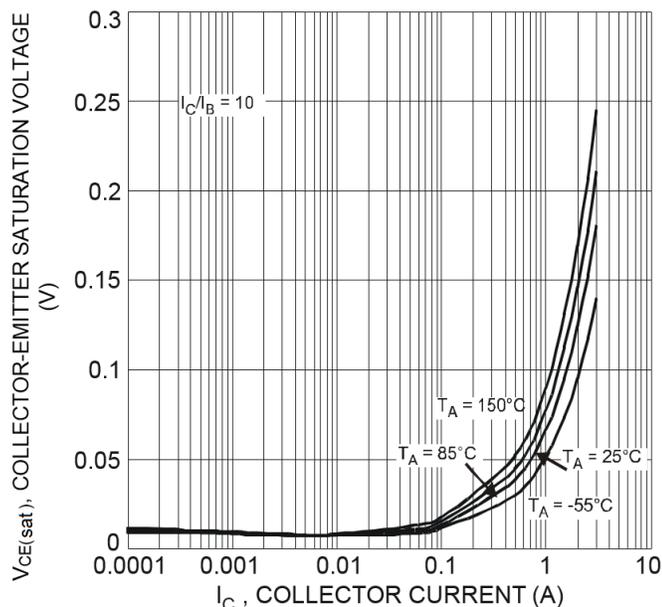


Figure 8. Saturation Voltage vs Collector Current

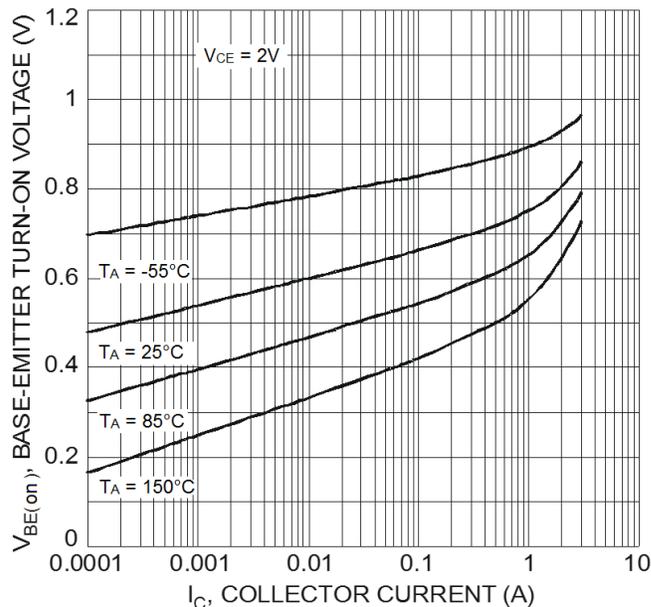


Figure 9. Typical Base-Emitter Turn-On Voltage vs Collector Current

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.) (continued)

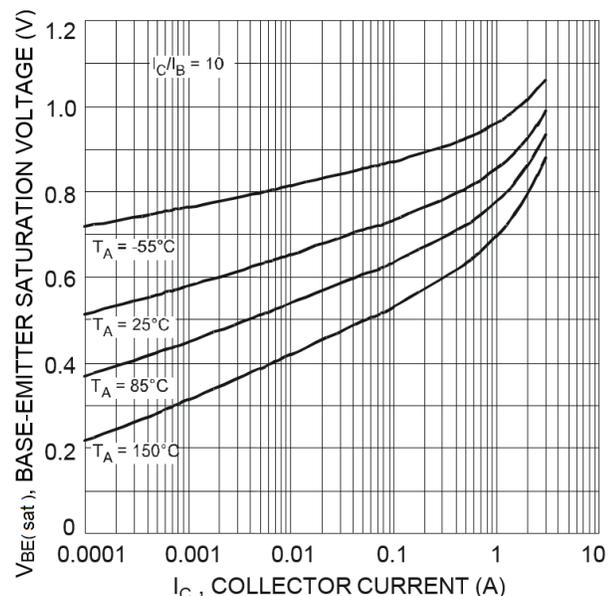


Figure 9. Typical Base-Emitter Saturation Voltage vs Collector Current

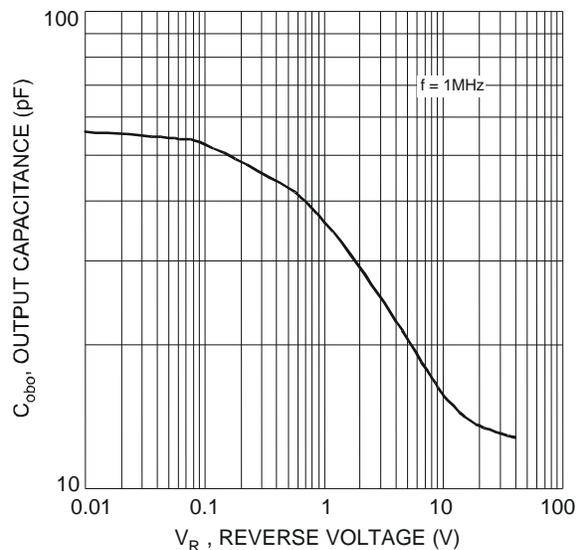


Figure 10. Typical Output Capacitance Characteristics

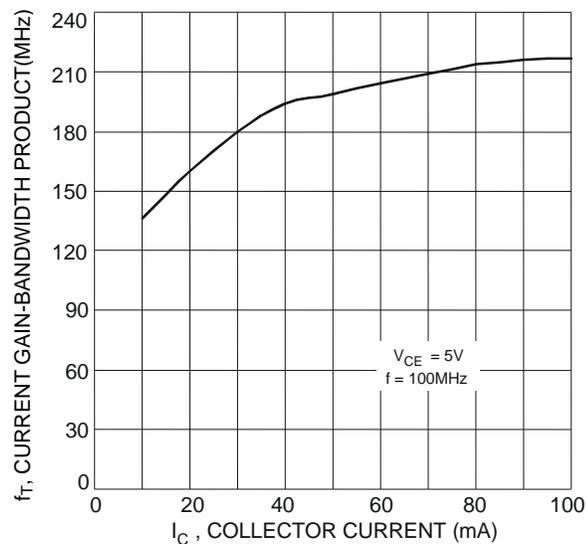
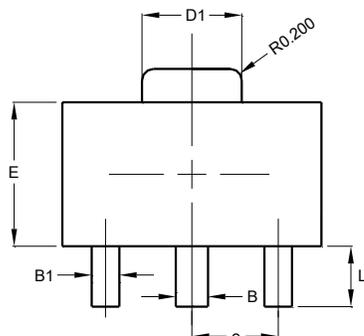


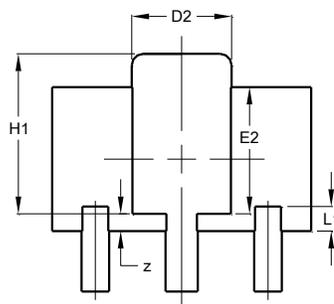
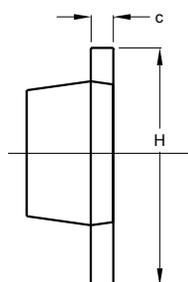
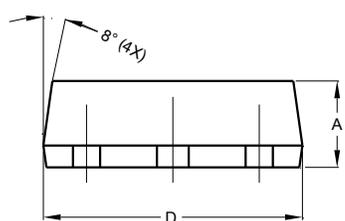
Figure 11. Typical Gain Bandwidth Product vs Collector Current

Package Outline Dimensions

SOT89



TOP VIEW

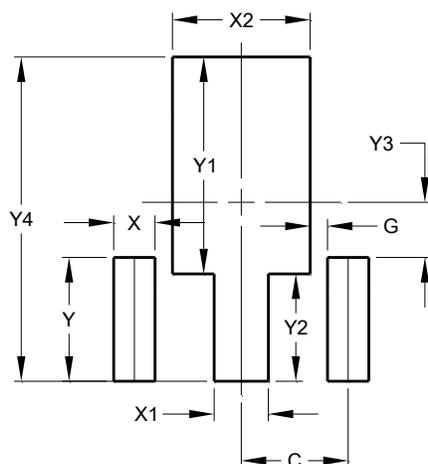


BOTTOM VIEW

| SOT89 | | | |
|----------------------|-------|-------|-------|
| Dim | Min | Max | Typ |
| A | 1.40 | 1.60 | 1.50 |
| B | 0.50 | 0.62 | 0.56 |
| B1 | 0.42 | 0.54 | 0.48 |
| c | 0.35 | 0.43 | 0.38 |
| D | 4.40 | 4.60 | 4.50 |
| D1 | 1.62 | 1.83 | 1.733 |
| D2 | 1.61 | 1.81 | 1.71 |
| E | 2.40 | 2.60 | 2.50 |
| E2 | 2.05 | 2.35 | 2.20 |
| e | - | - | 1.50 |
| H | 3.95 | 4.25 | 4.10 |
| H1 | 2.63 | 2.93 | 2.78 |
| L | 0.90 | 1.20 | 1.05 |
| L1 | 0.327 | 0.527 | 0.427 |
| z | 0.20 | 0.40 | 0.30 |
| All Dimensions in mm | | | |

Suggested Pad Layout

SOT89



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 1.500 |
| G | 0.244 |
| X | 0.580 |
| X1 | 0.760 |
| X2 | 1.933 |
| Y | 1.730 |
| Y1 | 3.030 |
| Y2 | 1.500 |
| Y3 | 0.770 |
| Y4 | 4.530 |